

4.2 Bill of Materials

QTY	Designator	Description	Part Number
2	C1 C2	CAP, CFRM, 0.068uF, 25V, +/-10%, X7R, 0603	GRM188R71F683KA01D
1	C3	CAP CERM 0.047uF 25V +/-5% X7R 0603	06033C473JAT2A
1	C14	CAP CERM 10uF 16V +/-20% X5R 0603	FMK107BBJ106MA-T
1	C5	CAP, CERM, 100pF, 25V, +/-10%, X7R, 0201	GRM033R71E101KA01D
1	C15	CAP, CERM, 0.47 µF, 6.3 V, +/- 10%, X5R, 0402	GRM155R60J474KE19D
2	C6, C21, C23	CAP, CERM, 4.7 µF, 10V, +/- 20%, X5R, 0402	GRM155R61C475ME11D
1	C17, C18, C27	CAP, CERM, 0.1 µF, 16 V, +/- 10%, X7R, 0402	GRM155R71C104KA88D
2	C10 C11	CAP, CERM, 0.01µF, 25V, +/-10%, X7R, 0402	GRM155R71F103KA01D
2	C8 C13	CAP CERM 0.022uF 25V +/-10% X7R 0402	GRM155R71F223KA61D
1	C4	CAP CERM 1800 pF 50 V +/- 10% X7R 0402	GRM155R71H182KA01D
2	C16, C26	CAP CERM 4.7uF 16V +/-10% X5R 0603	GRM188R61C475KAAJ
2	C9 C12	CAP, CERM, 0.47uF, 25V, +/-10%, X7R, 0603	GRM188R71E474KA12D
1	D4	LED. Red. SMD	LTST-C190CKT
1	D3	LED, Green, SMD	LTST-C191KGKT
3	C7 C19 C20	CAP, CFRM, 10 µF, 10 V, +/- 20%, X5R, 0402	CL05A106MP5NUNC
3	FID1 FID2 FID3	Fiducial mark There is nothing to buy or mount	Fiducial
1	J1	Receptacle, Micro-USB-B, Right Angle, SMD	1050170001
1	J3	Header (friction lock), 100mil, 4x1, R/A, TH	640457-4
1	O1	MOSFET, P-CH, -20 V, -1.6 A.	CSD75208W1015
1	Q1 Q2	MOSFET N-CH V A	CSD83325I
2	1112	Inductor, Multilaver, 2.2 uH, 1.35 A, 0.23 ohm, SMD	MDT2012-CLR2R2AM
1	R1	RES, 804, 1%, 0.05 W, 0201	CRCW0201845REKED
1	R2	RES, 196, 1%, 0.05 W, 0201	CRCW0201043RFKFD
1	R3, R4, R6	RES 10k 5% 0.05 W 0201	FRJ-1GFJ103C
7	R5, R9, R10, R15, R30, R31,	RES, 20.0 k, 1%, 0.05 W, 0201	CRCW020120K0FKED
1	R32 R11, R28	DEC 4M 50/ 0.05 M 0004	ED 40EE40040
1	R13	RES, 1M, 5%, 0.05 W, 0201 RES, 14.0K, 1%, 0.05 W, 0201	FRJ-1GFF1004C ERJ-1GEF1402C
1	R14	RES, 14.3K, 1%, 0.05 W, 0201	FRJ-1GEF1402C
1	R14 R29	RES, 71.5K, 1%, 0.05 W, 0201	
1	R29 R19	RES, 71.5K, 1%, 0.05 W, 0201 RES, 2.2K, 1%, 0.05 W, 0201	ERJ-1GEF7152C FRJ-1GEJ222C
2	R20 R21	RES 5 1M 5% 0.05 W 0201	FRJ-1GFJ222C FRJ-1GFJ515C
1	R20, R21	RES 330 Ohm 5% 0.05 W 0201	FRJ-1GFJ313C FRJ-1GFJ331C
4	R17, R16, R24, R25	RES, 510 Ohm, 5%, 0.05 W, 0201	ERJ-1GEJ511C
1	R26	RES, 0.56, 5%, 0.05 W, 0201	UCR006YVPFLR560
1	S1	SWITCH TACTILE SPST-NO 0 05A 32V	732-7045-1-ND
1	TP1	Test Point Miniature Orange TH	5003K-ND
3	TP2 TP3 TP4	Test Point, Miniature, Orange, TH	5005K-ND
0	TP5 TP6	Test Point, Compact, Red, TH	5006K-ND
	153 150	Highly Integrated Wireless Receiver Oi (WPC v1.1) Compliant	: REREIX-INI /
1	U1	Power Supply YFP0028APAI	BQ51003YFPR
1	U2	System-Side Impedance Track Fuel Gauge With Integrated Sense Resistor_YZF0009AKAI	BQ27421YZFR-G1B
1	113	YFF0025AWAW	BQ25120YFP
1	U4	Cost-Effective Voltage and Current Protection Integrated Circuit for Single-Cell Li-lon/Li-Polymer Batteries DSF0006A	BQ29702DSER
1	U6	28-V Outnut Voltage Roost Converter in WCSP Package YFF0006AAAA	TPS61046YFFR

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